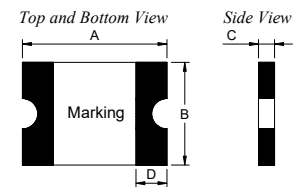


1、 Physical Dimensions(size of 1812)

Part Number	A		B		C		D	Marking
	Min	Max	Min	Max	Min	Max	Min	
KMSMD150/33	4.37	4.73	3.07	3.41	0.90	1.50	0.30	T150



2、 Electrical Characteristics

Part Number	I _H (A)	I _T (A)	V _{max} (V)	I _{max} (A)	T _{trip} (Max time to trip)		Pd _{typ} (W)	R _{min} (Ω)	R1 _{max} (Ω)
					Current(A)	Time(S)			
KMSMD150/33	1.50	3.00	33	100	8.0	1.50	1.2	0.030	0.180

I_H: Holding Current: maximum current at which the device will not trip in 25°C still air.

I_T: Tripping Current minimum current at which the device will trip in 25°C still air.

V_{max}: Maximum voltage device can withstand without damage at rated current.

I_{max}: Maximum fault current device can withstand without damage at rated voltage.

T_{trip}: Maximum time to trip(s) at assigned current.

Pd_{typ}: Rated working power.

R_{min}: Minimum resistance of device prior to trip at 25°C.

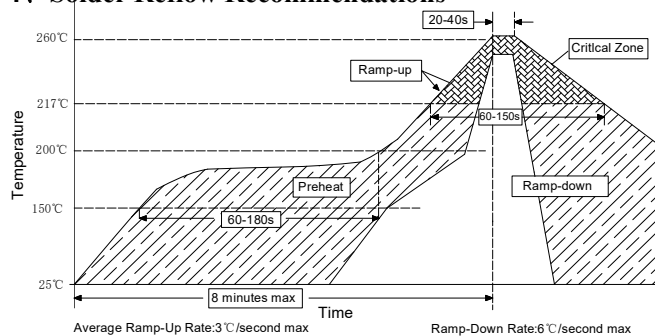
R1_{max}: Maximum resistance of device is measured one hours post reflow at 25°C.

Noted: All electrical function test is conducted after PCB mounted.

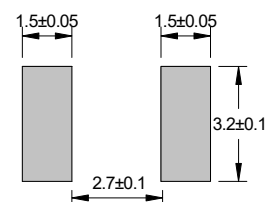
3、 Thermal Derating

KMSMD150/33	Maximum ambient operating temperature								
	-40°C	-20°C	0°C	25°C	40°C	50°C	60°C	70°C	85°C
Hold Current(A)	2.17	1.95	1.72	1.50	1.30	1.18	1.09	0.97	0.82
Trip Current(A)	4.34	3.90	3.44	3.00	2.60	2.36	2.18	1.94	1.64

4、 Solder Reflow Recommendations



Recommended Pad Layout(mm)



Notes: If reflow temperatures exceed the recommended profile, devices may not meet the performance requirements.

5、 Package Information

Packing quantity: 1500PCS/Reel

Note: Reel packaging per EIA-481-1 standard